

DESCRIPTION

The M5M54R04AJ is a family of 1048576-word by 4-bit static RAMs, fabricated with the high performance CMOS silicon gate process and designed for high speed application.

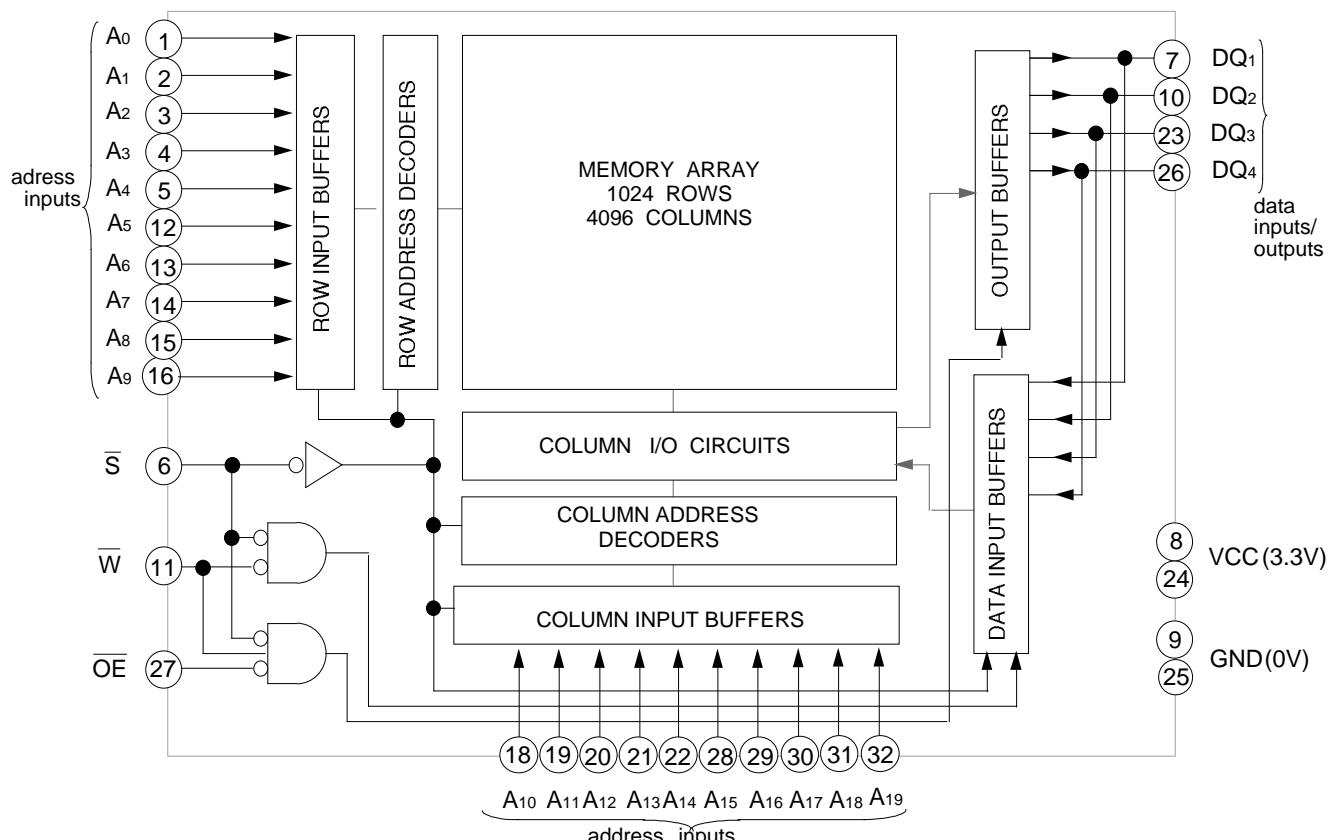
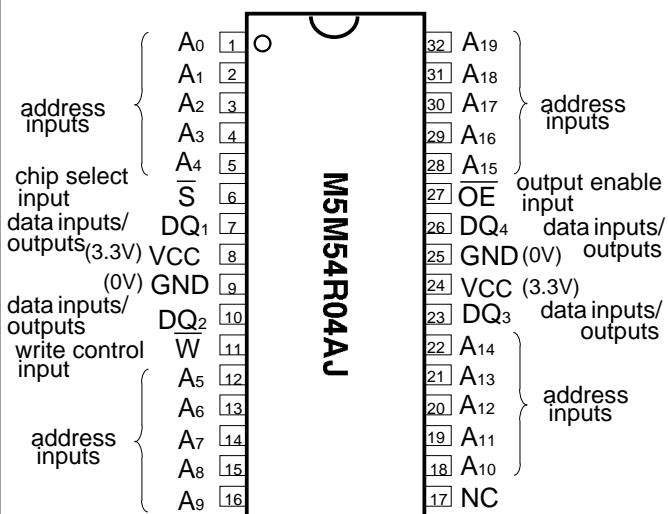
These devices operate on a single 3.3V supply, and are directly TTL compatible. They include a power down feature as well.

FEATURES

- Fast access time M5M54R04AJ-10 ... 10ns(max)
 M5M54R04AJ-12 ... 12ns(max)
 M5M54R04AJ-15 ... 15ns(max)
- Single +3.3V power supply
- Fully static operation : No clocks, No refresh
- Common data I/O
- Easy memory expansion by S
- Three-state outputs : OR-tie capability
- OE prevents data contention in the I/O bus
- Directly TTL compatible : All inputs and outputs

APPLICATION

High-speed memory units

BLOCK DIAGRAM**PIN CONFIGURATION (TOP VIEW)**

Outline 32P0K(SOJ)

PACKAGE

M5M54R04AJ : 32pin 400mil SOJ

MITSUBISHI LSIs

M5M54R04AJ-10,-12,-15

4194304-BIT (1048576-WORD BY 4-BIT) CMOS STATIC RAM

FUNCTION

The operation mode of the M5M54R04AJ is determined by a combination of the device control inputs S, W and OE. Each mode is summarized in the function table.

A write cycle is executed whenever the low level \bar{W} overlaps with the low level S. The address must be set-up before the write cycle and must be stable during the entire cycle.

The data is latched into a cell on the trailing edge of \bar{W} or S, whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output enable input OE directly controls the output stage. Setting the OE at a high level, the output stage is in a high impedance state, and the data bus

contention problem in the write cycle is eliminated.

A read cycle is excuted by setting \bar{W} at a high level and OE at a low level while S are in an active state ($S=L$).

When setting S at high level, the chip is in a non-selectable mode in which both reading and writing are disable. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by S.

Signal S controls the power-down feature. When S goes high, power dissipation is reduced extremely. The access time from S is equivalent to the address access time.

FUNCTION TABLE

S	W	OE	Mode	DQ	Icc
H	X	X	Non selection	High-impedance	Stand by
L	L	X	Write	Din	Active
L	H	L	Read	Dout	Active
L	H	H		High-impedance	Active

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Supply voltage	With respect to GND	- 2.0 ~ 4.6	V
VI	Input voltage		- 2.0 ~ VCC+0.5	V
VO	Output voltage		- 2.0 ~ VCC	V
Pd	Power dissipation	Ta=25°C	1000	mW
Topr	Operating temperature		0 ~ 70	°C
Tstg(bias)	Storage temperature(bias)		- 10 ~ 85	°C
Tstg	Storage temperature		- 65 ~ 150	°C

* Pulse width _3ns, In case of DC: - 0.5V

DC ELECTRICAL CHARACTERISTICS (Ta=0 ~ 70°C, Vcc=3.3V ^{+10%}/_{-5%}, unless otherwise noted)

Symbol	Parameter	Condition	Limits			Unit
			Min	Typ	Max	
VIH	High-level input voltage		2.0		Vcc+0.3	V
VIL	Low-level input voltage				0.8	V
VOH	High-level output voltage	I _{OH} = - 4mA	2.4			V
VOL	Low-level output voltage	I _{OL} = 8mA			0.4	V
I _I	Input current	VI= 0 ~ Vcc			2	uA
I _{OZ}	Output current in off-state	VI(S)=VIH VI/O= 0 ~ Vcc			2	uA
I _{CC1}	Active supply current (TTL level)	VI(S)=VIL other inputs=VIH or VIL Output-open(duty 100%)	AC	10ns cycle	190	mA
				12ns cycle	180	
				15ns cycle	160	
			DC		90	
I _{CC2}	Stand by current (TTL level)	VI(S)=VIH	AC	10ns cycle	90	mA
				12ns cycle	70	
				15ns cycle	60	
			DC		40	
I _{CC3}	Stand by current	VI(S)=Vcc - 0.2V other inputs VI - 0.2V or VI - Vcc - 0.2V			10	mA

Note 1: Direction for current flowing into an IC is positive (no mark).

CAPACITANCE ($T_a=0\sim70^\circ C$, $V_{cc}=3.3V^{+10\%}_{-5\%}$, unless otherwise noted)

Symbol	Parameter	Test Condition	Limit			Unit
			Min	Typ	Max	
C_I	Input capacitance	$V_I=GND, V_I=25mVrms, f=1MHz$			7	pF
C_O	Output capacitance	$V_O=GND, V_O=25mVrms, f=1MHz$			8	pF

Note 2: C_I, C_O are periodically sampled and are not 100% tested.

AC ELECTRICAL CHARACTERISTICS ($T_a=0\sim70^\circ C$, $V_{cc}=3.3V^{+10\%}_{-5\%}$, unless otherwise noted)

(1) MEASUREMENT CONDITION

- Input pulse levels $V_{IH}=3.0V, V_{IL}=0.0V$
- Input rise and fall time 3ns
- Input timing reference levels $V_{IH}=1.5V, V_{IL}=1.5V$
- Output timing reference levels $V_{OH}=1.5V, V_{OL}=1.5V$
- Output loads Fig.1, Fig.2

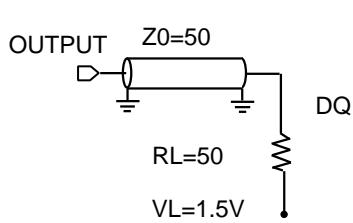


Fig.1 Output load

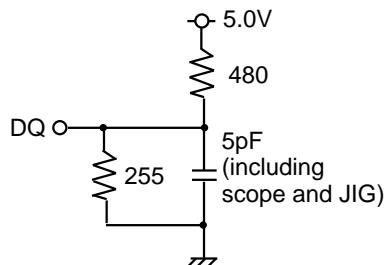


Fig.2 Output load for t_{en}, t_{dis}

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(2)READ CYCLE

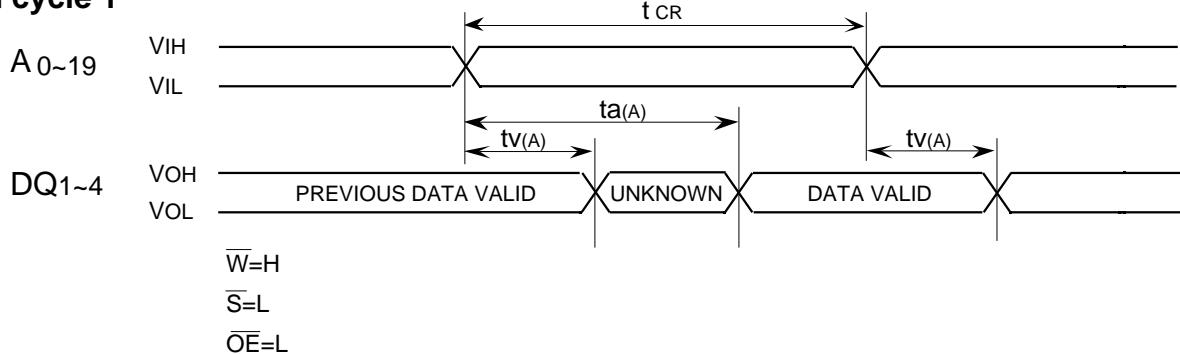
Symbol	Parameter	Limits						Unit	
		M5M54R04AJ-10		M5M54R04AJ-12		M5M54R04AJ-15			
		Min	Max	Min	Max	Min	Max		
t _{CR}	Read cycle time	10		12		15		ns	
ta(A)	Address access time		10		12		15	ns	
ta(S)	Chip select access time		10		12		15	ns	
ta(OE)	Output enable access time		5		6		7	ns	
tdis(S)	Output disable time after \bar{S} high	0	5	0	6	0	7	ns	
tdis(OE)	Output disable time after OE high	0	5	0	6	0	7	ns	
ten(S)	Output enable time after \bar{S} low	2		3		3		ns	
ten(OE)	Output enable time after OE low	0		1		1		ns	
tv(A)	Data valid time after address change	2		3		3		ns	
t _{PU}	Power-up time after chip selection	0		0		0		ns	
t _{PD}	Power-down time after chip selection		10		12		15	ns	

(3)WRITE CYCLE

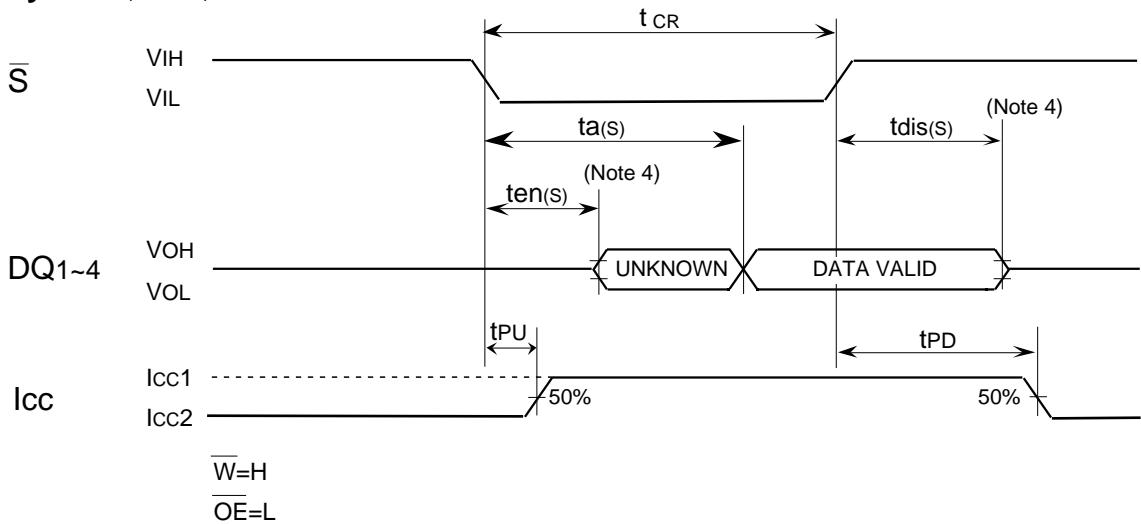
Symbol	Parameter	Limits						Unit	
		M5M54R04AJ-10		M5M54R04AJ-12		M5M54R04AJ-15			
		Min	Max	Min	Max	Min	Max		
t _{CW}	Write cycle time	10		12		15		ns	
tw(W)	Write pulse width (OE low)	10		12		15		ns	
tw(W)	Write pulse width($\bar{O}E$ high)	8		10		10		ns	
tsu(A)1	Address setup time(\bar{W})	0		0		0		ns	
tsu(A)2	Address setup time(\bar{S})	0		0		0		ns	
tsu(S)	Chip select setup time	8		10		10		ns	
tsu(D)	Data setup time	5		6		7		ns	
th(D)	Data hold time	0		0		0		ns	
trec(W)	Write recovery time	1		1		1		ns	
tdis(W)	Output disable time after \bar{W} low	0	5	0	6	0	7	ns	
tdis(OE)	Output disable time after $\bar{O}E$ high	0	5	0	6	0	7	ns	
ten(W)	Output enable time after \bar{W} high	0		0		0		ns	
ten(OE)	Output enable time after $\bar{O}E$ low	0		0		0		ns	
tsu(A- $\bar{W}H$)	Address to \bar{W} High	8		10		10		ns	

(4)TIMING DIAGRAMS

Read cycle 1



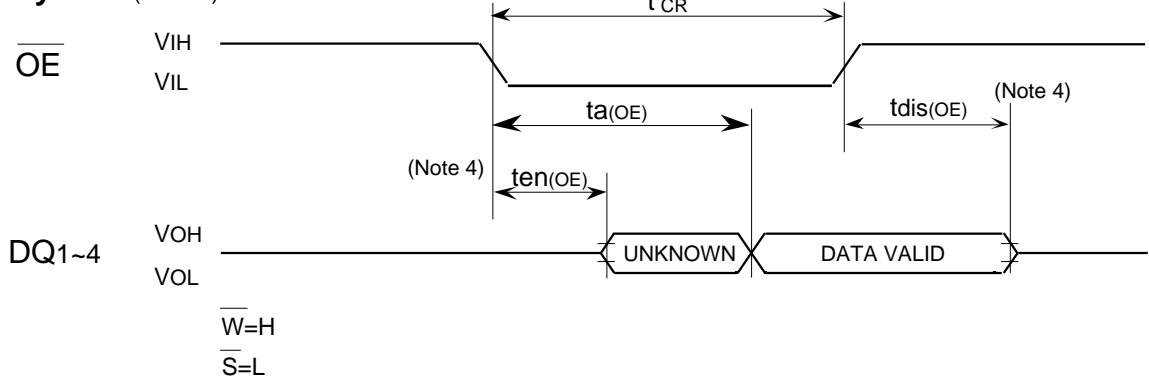
Read cycle 2 (Note 3)



Note 3. Addresses valid prior to or coincident with \bar{S} transition low.

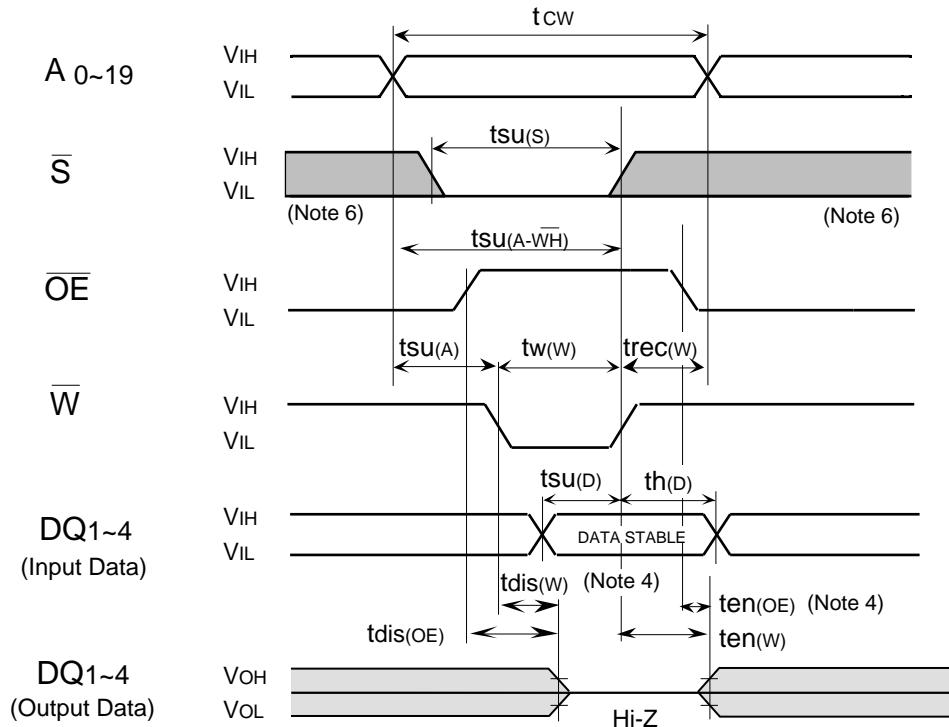
4. Transition is measured $\pm 500\text{mv}$ from steady state voltage with specified loading in Figure 2.

Read cycle 3 (Note 5)

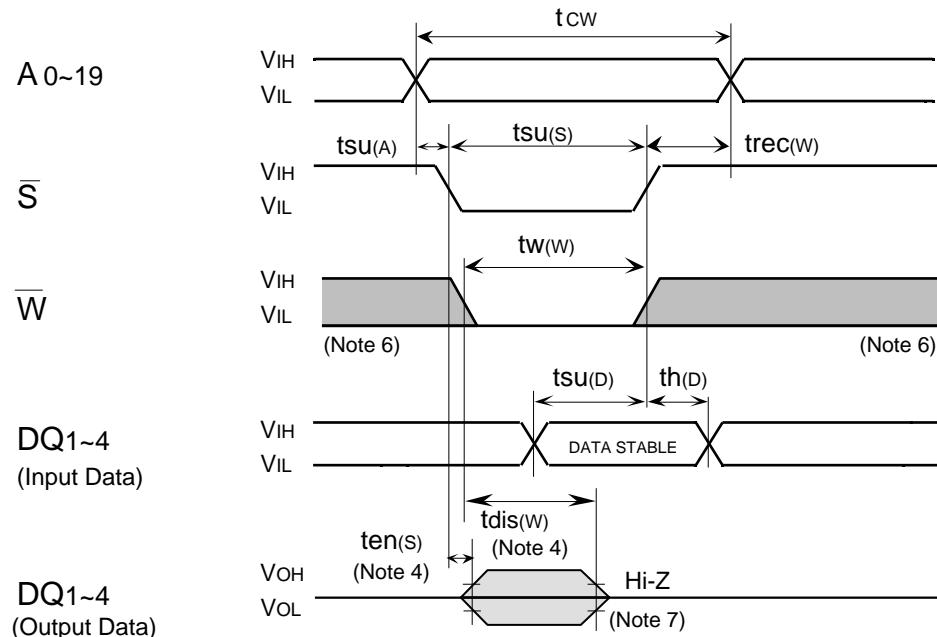


Note 5. Addresses and \bar{S} valid prior to \bar{OE} transition low by $(ta(A)-ta(OE))$, $(ta(S)-ta(OE))$

Write cycle (\bar{W} control mode)



Write cycle (\bar{S} control)



Note 6: Hatching indicates the state is don't care.

7: When the falling edge of \bar{W} is simultaneous or prior to the falling edge of \bar{S} , the output is maintained in the high impedance.

8: ten , $tdis$ are periodically sampled and are not 100% tested.